

TSMC-03-130/092



April 9, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

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Subject: | Serial No. 10/781,169 02/18/04 |

Hsin-Hui Lee et al.

IMPROVING THE UNDERFILLING EFFICIENCY
BY MODIFYING THE SUBSTRATE DESIGN
OF FLIP CHIPS

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.


The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
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P.O. Box 1450, Alexandria, VA 22313-1450, on April 12, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 4/12/04

TSMC-03-130/092

U.S. Patent 6,570,261 to Farquhar et al., "Method and Apparatus for Injection Molded Flip Chip Encapsulation," describes an automatic freeway incident detection system and method using artificial neural network and genetic algorithms.

U.S. Patent 5,990,545 to Schueller et al., "Chip Scale Ball Grid Array for Integrated Circuit Package," describes a chip scale ball grid array for integrated circuit package.

U.S. Patent 6,414,849 to Chiu, "Low Stress and Low Profile Cavity Down Flip Chip and Bond BGA Package," describes a low stress and low profile cavity down flip chip and wire bond BGA package.

U.S. Patent Application Publication, US 2002/0011656 A1 to Swanson et al., "Semiconductor Device Protective Overcoat with Enhanced Adhesion to Polymeric Materials and Method of Fabrication," describes a semiconductor device protective overcoat with enhanced adhesion to polymeric materials and method of fabrication. 2

Sincerely,



Stephen B. Ackerman,
Reg. No. 37761

**INFORMATION DISCLOSURE CITATION
IN AN APPLICATION**

APR 15 2004

(Use several sheets if necessary)

Docket Number (Optional)

Application Number

TSMC-03-130/092 10/781,169

Applicant

Hsin-Hui Lee et al.

Filing Date

02/18/04

Group Art Unit

U. S. PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	ALSO DATE IF APPROPRIATE
6570261	5/27/03	Farguhar et al.	257	778	4/8/02
5990545	11/23/99	Schueler et al.	257	697	12/2/96
6414849	7/2/02	Chiu	361	760	10/29/99

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portmox Pages, Etc.)

-	U.S. Patent App. Pub. US 2002/0011656 A1 to Swanson et al., Pub. Date 1/31/02, Filed 6/2/01, U.S.C.I. 257/697.

EXAMINER

DATE COMPLETED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.